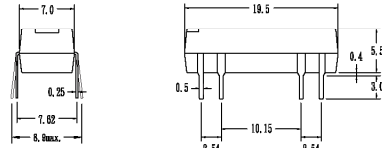


**Features**

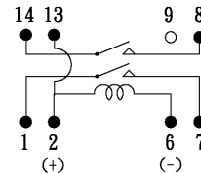
1. Molded epoxy body.
2. Dip type construction with the same terminal pitch as ICs or TTLs simplifies PC board designing. In addition, the high sensitivity allows direct driving by TTL, etc.
3. Automatic insertion compatible.
4. Sealed construction permits automatic flow soldering and cleaning.
5. Diode & Magnetic shield are available.

**Outside Dimension:Unit (mm)**



TOLERANCE : ± 0.1mm

**Schematic:Top View**



**Coil Ratings**

(AT 20°C)

Parameter	Rating	Unit
Coil Resistance	500	$\Omega$ ( ±10%)
Nominal Coil Voltage	12	VDC
Maximum Continuous Voltage	20	VDC
Must Operate	9	VDC
Must Release	1.2	VDC
Rated Current	24	mA

**Electrical Characteristics**

Parameter	Rating	Unit
Contact Resistance	100	m $\Omega$ (max)
Operate Time	0.5	ms(max)
Bounce Time	0.5	ms(max)
Release Time	0.2	ms(max)
Insulation Resistance (100VDC)	10 <sup>11</sup>	$\Omega$ (min)
Power	10	VA(max)
Switching Voltage	200	VDC(max)
Switching Current	0.5	A(max)
Carry Current	1.0	A(max)
Breakdown Voltage ( Across Open Contact )	250	VDC(min)
( Between Coil & Contact )	500	VDC(min)
Life Expectancy (Signal Level)	10 <sup>8</sup>	
Operating Temp	-40 to 85	°C
Storage Temp	-50 to 125	°C
Resonant Frequency	3.5	KHZ
Vibration ( 10-2000HZ )	20	g(max)
Minimum Permissible Load	100	mVDC 10 $\mu$ A